

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1tc1452cn8#pbf

(Engineering Calculation)

PDIP

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**TOTAL MASS (g) : 0.501133**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.003908	1000000	7798.32373047		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000163	1000000	325.262756348		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.149760	975000	298842.59375		
		Iron (Fe)	7439-89-6	0.003686	24000	7355.32763672		
		Phosphorus (P)	7723-14-0	0.000046	300	91.7919387817		
		Zinc (Zn)	7440-66-6	0.000108	700	215.511505127		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.153600</b>	<b>1000000</b>	<b>306505.25</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.012410	1000000	24764.4492188		
		<b>External Plating Total:</b>				<b>0.012410</b>	<b>1000000</b>	<b>24764.4492188</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001228	1000000	2450.44555664		
<b>Internal Plating Total:</b>				<b>0.001228</b>	<b>1000000</b>	<b>2450.44555664</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001088	750000	2171.07885742		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000363	250000	724.358154297		
<b>Die Attach Total:</b>				<b>0.001451</b>	<b>1000000</b>	<b>2895.43701172</b>		
Encapsulation	FILLED EPOXY RESIN	Resin (EP)		0.078741	240000	157125.84375		
		Bromine (Br)	40039-93-8	0.003281	10000	6547.16015625		
		Silica (SiO2)	60676-86-0	0.236222	720000	471375.5625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.009843	30000	19641.4785156		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000000	0	0		
		<b>Encapsulation Total:</b>				<b>0.328087</b>	<b>1000000</b>	<b>654690</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000286	1000000	570.706359863		
					<b>TOTAL MASS (g) :</b>	<b>0.501133</b>		